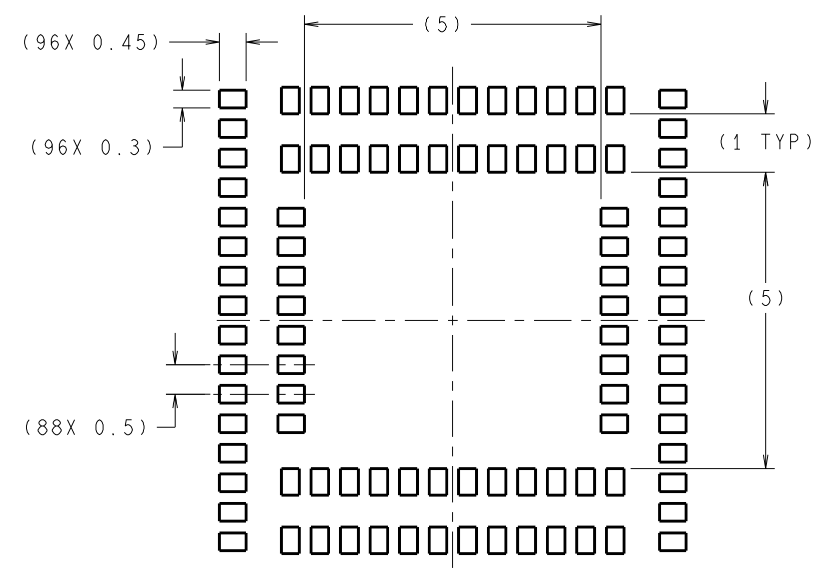
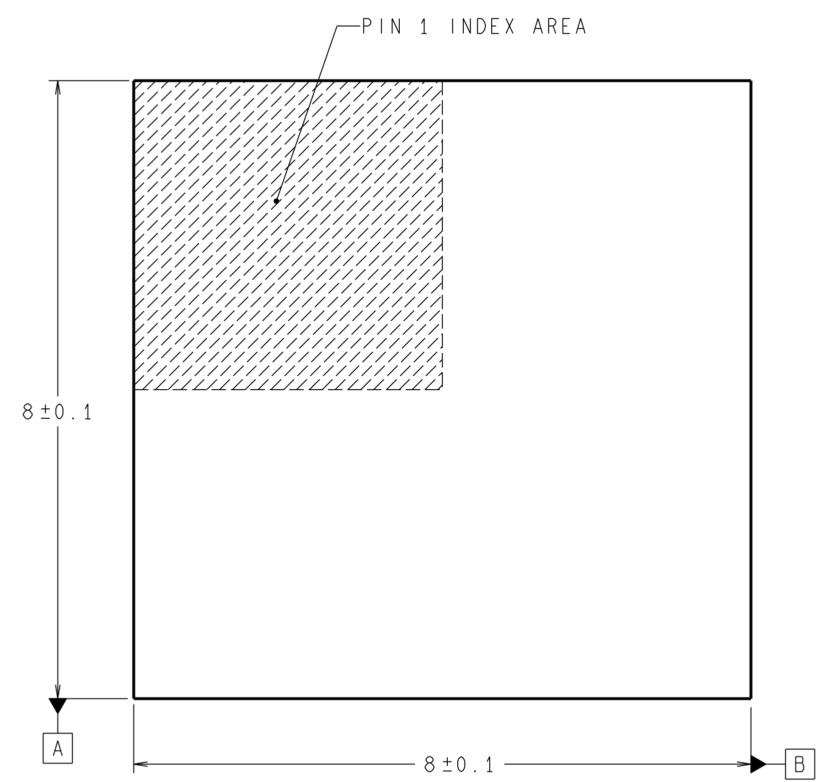
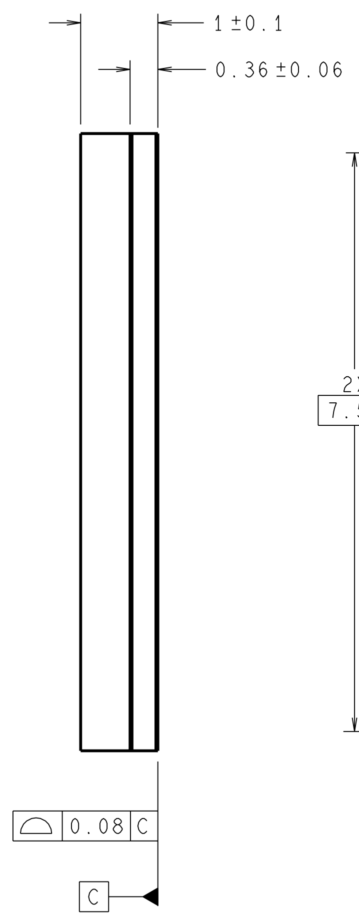
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12334	12/13/1999	TL/GN

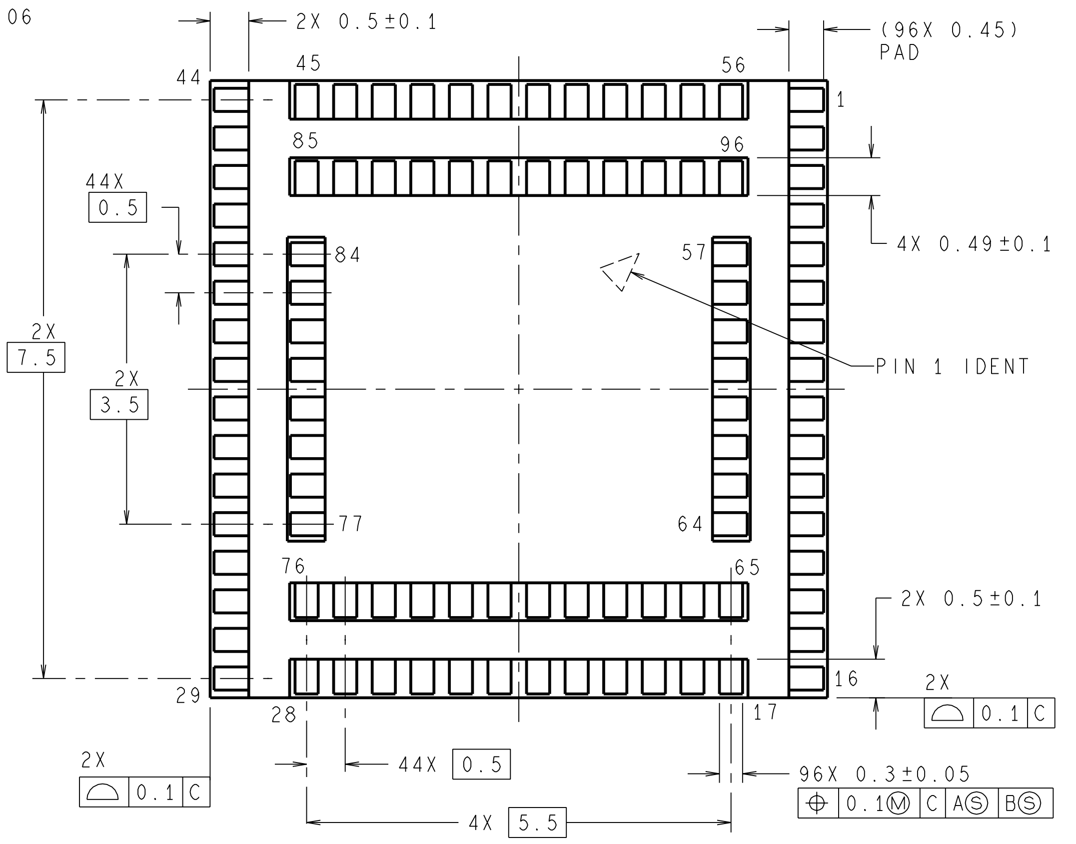


RECOMMENDED LAND PATTERN
1:1 RATIO WITH PACKAGE SOLDER PADS

DIMENSIONS ARE IN MILLIMETERS







NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL: BT RESIN CCL-HL832 WITH TAIYO PSR4000 AUS5 SOLDER MASK.
2. PLATING: Cu 15 TO 20 MICROMETERS (FULL)
   Ni 10 ± 5 MICROMETERS (LEADS ONLY)
   Au 1 ± 0.5 MICROMETER (LEADS ONLY)
3. REFERENCE JEDEC MO-208, VARIATION MMEB, DATED DECEMBER 1999.

APPROVALS	DATE
DRAWN T. LEQUANG	12/13/1999
DFTG. CHK. MARTA SUCHY	12/13/1999
ENGR. CHK. GLENN NARVAEZ	12/13/1999

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

CSP, PLASTIC, LAMINATED, 8 x 8 x 1 mm BODY, 96 L, 0.5 mm PITCH

PROJECTION
INCH [MM]

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	(SC)MKT-SLB96A	A

FORMERLY: N/A

SHEET 1 of 1